

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die		Lead Dioxide (PbO2)	1309-60-0	0.00369	0.93	0.0558
	Doped silicon	Silicon (Si)	7440-21-3	0.39295	99.07	5.9442
Subtotal				0.39664	100	6
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.02152	10.0	0.32558
	Silver alloy	Silver (Ag)	7440-22-4	0.0043	2.0	0.06512
	Lead alloy	Lead (Pb)	7439-92-1	0.18941	88.0	2.86513
Subtotal				0.21523	100	3.25583
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.56775	100.0	8.58835
	Subtotal			0.56775	100	8.58835
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00923	0.03	0.13965
	Copper alloy	Iron (Fe)	7439-89-6	0.03385	0.11	0.51205
	Copper alloy	Copper (Cu)	7440-50-8	30.72983	99.86	464.8483
Subtotal				30.77291	100	465.5
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.32062	100.0	4.85
	Subtotal			0.32062	100	4.85
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	5.41815	8.0	81.96
	Filler	Silica fused	60676-86-0	54.85874	81.0	829.845
	Metal hydroxide	Metal hydroxide		0.47409	0.7	7.1715
	Carbon Black	Carbon black	1333-86-4	0.20318	0.3	3.0735
	Polymer	Epoxy resin system		6.77268	10.0	102.45
Subtotal				67.72684	100	1024.5
Total				99.99999	100	1512.69418

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